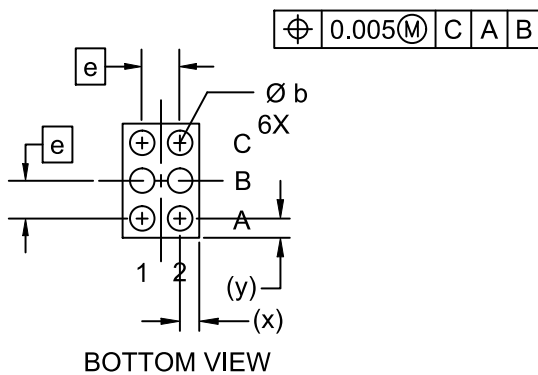
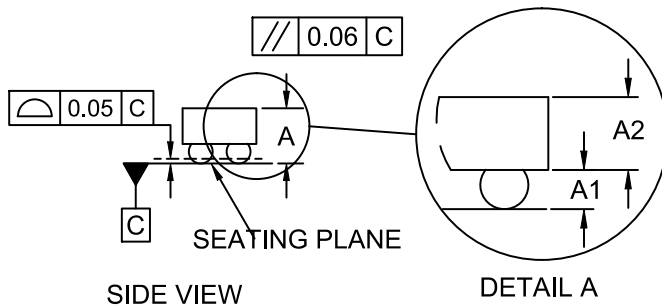
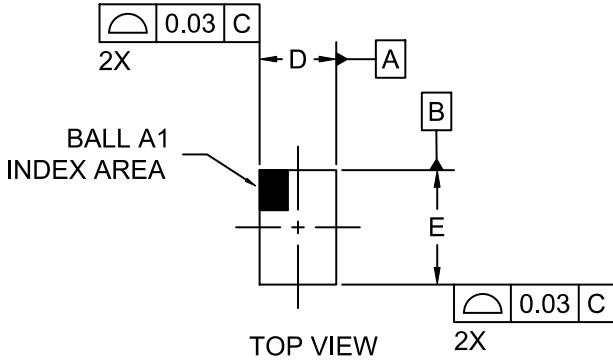


**WLCSP6 0.88x1.23x0.458**  
CASE 567VM  
ISSUE O

  
**SCALE 4:1**

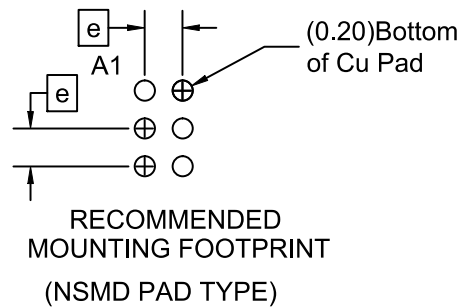
DATE 28 NOV 2017



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	.419	.458	.497
A1	.187	.208	.229
A2	.232	.250	.268
b	0.240	0.260	0.280
D	0.85	0.88	0.91
E	1.200	1.230	1.260
e	0.40 BSC		
x	0.225	0.240	0.255
y	0.200	0.215	0.230



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